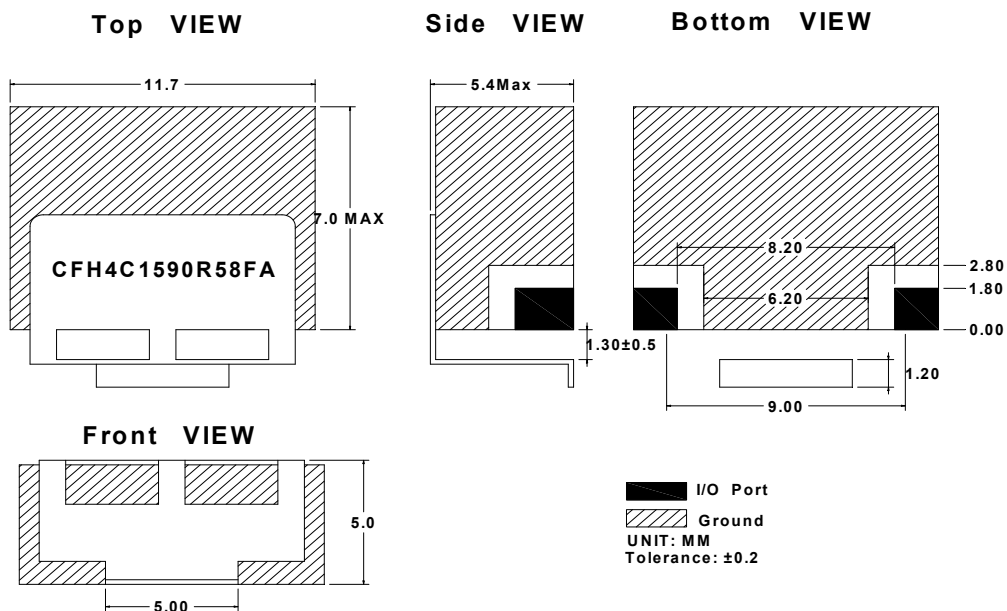
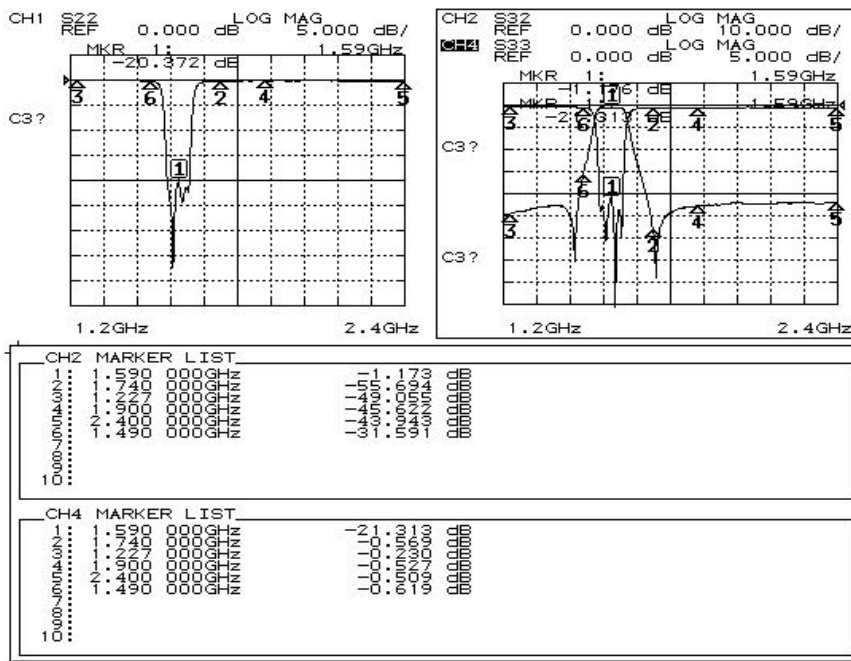


Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	1590.0	MHz
Bandwidth [BW]	$f_o \pm 29.0$ [1561.0 ~ 1619.0]	MHz
Insertion Loss in BW	2.0	dB max
Ripple in BW	0.5 @ $f_o \pm 13.0$	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	40.0 dB min @ $f_o \pm 100.0$ [1490.0 ~]	MHz
	50.0 dB min @ $f_o \pm 150.0$ [1740.0 ~]	MHz
	50.0 dB min @ $f_o \pm$ [1227.0 ~]	MHz
	50.0 dB min @ $f_o \pm$ [1900.0 ~]	MHz
	50.0 dB min @ $f_o \pm$ [2400.0 ~]	MHz
Group Delay Variation		ns max
Input Power	1.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

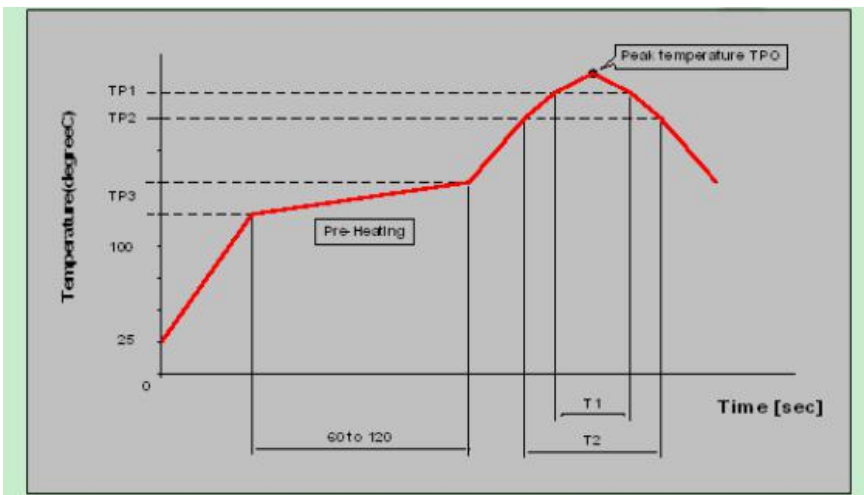
Mechanical Specification





 Recommended PC Board Pattern

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device
 Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180